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APPLICANT : ASAHI CHEM RES LAB LTD;

INVENTOR : IWASA SANDAI;

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TITLE : SOLDERABLE CONDUCTIVE PASTE

ABSTRACT : PURPOSE: To improve solderability and economic property by using a specified ester as a solderability giving agent.

CONSTITUTION: When a higher fatty acid ester of polyglyceline is used as a solderability giving agent, a satisfactory soldering can be applied on the whole surface of its hardened film, and this film never loses solderability by the change with the lapse of time. Further, the addition of a solder powder enhances these characteristics more and prevents the soldering consumption of solder silver powder, providing a solderable conductive paste having long-term solderability and high economic property.

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